SynFlex Elektro GmbH
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WEVOSIL 26040 FL

Solvent-free, two-component silicone-based gap filler with high thermal conductivity .

Attributes

The resulting soft-elastic moulding material is characterized by good low-temperature flexibility and excellent behaviour in the temperature shock test. The system contains mineral fillers, which can be abrasive.
Recommended temperature range: -60 °C to +200 °C.
The resin is processed together with WEVOSIL 26040 FL B.

Application

- Pressure-sensitive electrical components
- Complete assemblies in SMD technology
- Thermally conductive adhesive and encapsulation

Standards

- Temperature application range -60 °C - +200 °C

Delivery forms

30 kg containers

Color

WEVOSIL 26040 FL A: Natural
WEVOSIL 26040 FL B: Blue

Storage

Polymer (A-component) and crosslinker (B-component) must be stored dry and at a temperature of 5 °C to 30 °C and not in the open air. The containers should be stored upright and not
directly on the cold floor (floor temperature not below 5 °C). WEVOSIL 26040 has a shelf life of 6 months after production.
At temperatures above 25 °C, the settling of the fillers contained in the casting compound is accelerated. The potting compound is then more difficult to homogenize.

Hardening

- Pot life: 50-70 minutes at room temperature, depending on layer thickness and casting volume.
- Curing time: 4 hours at room temperature, or 1 hour at 100 °C

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- Final chemical curing: several days at room temperature

Curing notes:

- Excessive humidity has a damaging effect on the uncured compound. If necessary, curing should take place in an air-conditioned room, a container with low humidity or in an oven.
- Curing at an elevated temperature (50 - 100°C) accelerates the curing reaction and can influence the adhesion of the potting compound to the walls of the component.
- The WEVOSIL 26040 FL casting compound reaches its final hardness after a few days at room temperature.
- After approx. 4 hours curing at room temperature (or 1 h @ 100 °C) approx. 90 - 95 % of the curing takes place. To achieve the final hardness, post-curing can then be carried out for 2 hours at 165 - 180 °C. However, this last step is not absolutely necessary. After a few days, the casting compound reaches its final hardness even at room temperature (depending on the system).
- Electrical tests of the component quality can usually be carried out after the first curing (4 hours at room temperature or 1 h @ 100 °C).

Protection

Our products are intended exclusively for industrial use. For further details, please read the safety data sheet.

Processing

Our processing instructions please find here.

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General	Unit of measure	Condition	Value	Test method
Mixing ratio	weight-%		100:100	
Pot lilfe	min	25 °C	50-70	
Curing time	h	25 °C	4	
Curing time	h	100 °C	1	

Mechanical	Unit of measure	Condition	Value	Test method
Density	g/cm³	WEVOSIL 26040 FL A	3.08-3.12	
Density	g/cm³	WEVOSIL 26040 FL B	3.08-3.12	
Viscosity	mPas	WEVOSIL 26040 FL B / 22 °C	100,000-150,000	
Viscosity	mPas	22 °C, WEVOSIL 26040 FL A	100,000-150,000	
Mixture viscosity		22 °C	100,000-150,000	
Hardness		Shore 00	60-80	ISO 48-4
Water absorption	%	30 d, RT	0.1	
Elongation at break	%		30	ISO 527-2

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Thermal	Unit of measure	Condition	Value	Test method
Glass transition temperature	°C		-100	TMA
Thermal conductivity	W/m*K		4.0	ISO 22007-2:2008

Electrical	Unit of measure	Condition	Value	Test method
Dielectric strength	kV/mm		>20	DIN EN 60243
Dielectric constant ε at 50 Hz, 23 °C			7.0	DIN EN 60250
Dielectric constant; at 1 kHz, 23 °C			6.78	DIN EN 60250
Dielectric constant ε at 1 MHz, 23 °C			6.51	DIN EN 60250
Volume resistance specific at 23 °C, 50 % r.h.	Ωxcm		>10^13	DIN EN 62631-3-1:2016
Surface resistivity at 23°C and 50 % r.h.	Ω		>10^14	DIN EN 62631-3-2:2016